

TMP103

Low power digital temperature sensor

Features

 Multiple Device Access (MDA) -- Global read and write operations •Temperature range: -40°C to +125°C •Temperature measurement accuracy: ±1°C (-40°C ~ +125°C) Package: 4-Ball WCSP (DSBGA) Supply voltage TMP103A:1.4V ~ 2.8V TMP103B: 1.4V ~ 3.6V Low static current Normal operation: $\leq 3\mu A$ (0.25Hz) Off mode: ≤1µA Resolution TMP103A:8Bits TMP103B: 11Bits •Digital output: compatible with SMBus [™] and IC² interfaces

Applications

- Phone
- Laptop
- Solid State Drive (SSDs)
- Server
- Set top box
- Low power environment
- Sensor

Description

The TMP103 series temperature sensors are all in 4-Ball wafer-level packages, of which the TMP103A has a resolution of 1°C and the TMP103B has a resolution of 0.125°C.

The two-wire interface of the TMP103 series is compatible with SMBus and IC² communication modes, and supports multi-chip access (MDA) commands, which can realize the communication between the host and multiple chips on the bus at the same time, without sending separate read and write commands to each TMP103 series chip. TMP103A supports up to 8 different address chips to be mounted on a main line, and TMP103B supports 16 different address chips to be mounted.

The TMP103 series is suitable for the system with limited temperature measurement area, temperature sensitivity, and multi-temperature area measurement and monitoring. The rated operating temperature range of theTMP103 series is -40° C ~ $+125^{\circ}$ C.



TMP103 Application Diagram



Pin Configuration and Functions



Pin Functions

PIN		DESCRIPTION			
NO.	NAME	DESCRIPTION			
A1	V+	Supply voltage.			
A2	GND	Ground.			
B1	SDA	Serial data input. Open-drain output, requires a pull-up resistor.			
B2	SCL	Serial clock. Open-drain output, requires a pull-up resistor.			



Specifications

Absolute Maximum Ratings

	MIN	МАХ	UNIT	
Supply Voltage, V+		4	V	
Voltage at SCL, SDA	0.2	((V +) + 0.3)	V	
	0.3	and ≤4	v	
Operating Temperature	- 55	160	°C	
Junction Temperature		150	°C	
Storage Temperature	- 60	150	°C	

In the course of using the TMP103 series, Over operating free-air temperature range (unless otherwise noted). Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.

ESD Ratings

		Value	UNIT
Electrostatic	Human Body Mode (HBM), per ANSI/ESDA/JEDEC JS-001	±5000	V
Discharge, V _{ESD}	Machine Mode (MM), per JEDEC-STD Classification	300	V

Recommended Operating Conditions

		MIN	NOM	MAX	UNIT	
Power ourply voltage V+	TMP103A	1.4		2.8	N	
Power supply voltage v+	TMP103B	1.4		3.6	V	
Operating temperature range T		- 40		125	°C	



Electrical Characteristics

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Unless otherwise specified, the following data are the characteristics of the TMP103 series chip at the temperature of $+25^{\circ}$ C and the supply voltage in the range of $1.4V \sim 2.8V$ (TMP103A) / $1.4V \sim 3.6V$ (TMP103B).

PARAMETER	TEST CONDITONS	MIN	ТҮР	MAX	UNIT		
Operating Temperature Range		- 40		125	°C		
	-10°C to 100°C, V+ = 1.8V	2 -	0	2	°C		
Accuracy (Temperature	-40°C to 125°C, V+ = 1.8V	- 3	Plus or	3	°C		
Error)	vs Supply	0.5	+ / - 0.2	0.5	°C/V		
	71/2/004		1		°C		
Resolution	IMP103A		8		Bits		
Resolution	THE		0.125		°C		
	IMP103B		11		Bits		
Conversion Time			26	35	ms		
	CR1 = 0, CR0 = 0		0.25		- Conv/s		
Conversion Modeo	CR1 = 0, CR0 = 1		1				
Conversion modes	CR1 = 1, CR0 = 0		4				
	CR1 = 1, CR0 = 1		8		-		
Timeout Time			30	40	ms		
Communication Frequency		0.001		2.75	MHz		
Power supply operating voltage	TMP103A	1.4		2.8			
	TMP103B	1.4		3.6			
	Bus not		4 5	3			
Augusta Ouissant Current I	activated, CR1=0, CR0=0(default)		1.5				
Average Quiescent Current, IQ	Bus activated, SCL frequency=400 kHz		15		- Mu A		
	Bus activated,SCL frequency=3.4 MHz		85				
	Bus is not activated, V+=1.8V	0.5					
Shutdown Current, I _{SD}	Bus activated, SCL frequency=400 kHz		10		Mu A		
	Bus activated,SCL frequency=3.4 MHz		80				



Detailed Description

Device Functional Modules





DSBGA-4



TOP VIEW WITH BUMP SIDE UP



WAFER NOTCH DOWN

		CUSTOMER		DEVICE NAME	TYPE		
Min bump pitch of die(um)	400		DSJF			1P1M-	-CSP
Min bump pitch of between dies(um)	480	DRAWN	Amy. xu	DWG. No. MS2	210021		A
Number of total bumps	4	CHECK	Brain.chen	MASK TYPE 6inch SMEE	UNIT UM	SHEET	2



Ordering information

Order code	Package	Baseqty	Deliverymode	Marking	
UMW TMP103AYFFR	DSBGA-4	3000	Tape and reel	TA UMW	
UMW TMP103BYFFT	DSBGA-4	3000	Tape and reel	TB UMW	